

CLAIMS

What is claimed is:

1. A method for producing laminates for printed wiring boards using protective-carrier sheeting, the method comprising the steps of:
- (a) sandwiching a layer of protective-carrier sheeting between two layers of conductive foil extended from conductive-foil sources;
 - (b) covering each of the conductive-foil layers with a dielectric layer to sandwich each conductive-foil layer between a dielectric layer and a layer of protective-carrier sheeting; and
 - (c) repeating steps (a) and (b) and stacking the layers to form a book without use of adhesive or mechanical attachment between layers.
2. The method of claim 1, wherein the conductive foil comprises copper.
3. The method of claim 2, wherein the layer of protective-carrier sheeting has a thickness in the range from about 0.08 mm to about 0.5 mm.
4. The method of claim 3, wherein the layer of protective-carrier sheeting has a thickness in the range from 0.1 mm to 0.25 mm.
5. The method of claim 3, wherein the conductive-foil sources are rolls of copper foil.
6. The method of claim 5, wherein the dielectric layer comprises prepreg.
7. The method as recited in claim 5, further comprising the steps of:
- (d) placing the book in a lamination press; and
 - (e) pressing the book without inclusion of an adhesive or mechanical attachment between the protective-carrier sheeting and conductive foil.

8. The method of claim 3, wherein the protective-carrier sheeting comprises aluminum.
9. The method of claim 8, further comprising the step of unwinding the protective-carrier sheeting from a roll.
10. The method of claim 9, wherein the conductive foil and the protective-carrier sheeting are unwound from the same roll.
11. The method of claim 9, wherein the conductive foil and the protective-carrier sheeting are unwound from separate rolls.
12. The method of claim 8, wherein the protective-carrier sheeting is provided in the form of separate sheets.
13. A method for producing laminates for printed wiring boards using protective-carrier sheeting, the method comprising the steps of:
- (a) sandwiching a dielectric layer between two layers of conductive foil extended from conductive-foil sources;
 - (b) covering at least one of the layers of conductive foil with a layer of protective-carrier sheeting;
 - (c) repeating steps (a) and (b) and stacking the layers to form a book, wherein each layer of conductive foil is sandwiched between a dielectric layer and a layer of protective-carrier sheeting without use of adhesive or mechanical attachment between layers.
14. The method of claim 13, wherein the conductive foil comprises copper.
15. The method of claim 14, wherein the layer of protective-carrier sheeting has a thickness in the range from about 0.08 mm to about 0.5 mm.

16. The method of claim 15, wherein the layer of protective-carrier sheeting has a thickness in the range from 0.1 mm to 0.25 mm.
17. The method of claim 15, wherein the conductive-foil sources comprise rolls of copper foil.
18. The method of claim 15, wherein the dielectric layer comprises prepreg.
19. The method as recited in claim 15, further comprising the steps of:
 - (d) placing the book in a lamination press; and
 - (e) pressing the book without inclusion of an adhesive or mechanical attachment between the protective-carrier sheeting and conductive foil.
20. The method of claim 15, wherein the protective-carrier sheeting comprises aluminum.
21. The method of claim 20, further comprising the step of unwinding the protective-carrier sheeting from a roll.
22. The method of claim 21, wherein the conductive foil and the protective-carrier sheeting are unwound from the same roll.
23. The method of claim 21, wherein the conductive foil and the protective-carrier sheeting are unwound from separate rolls.
24. The method of claim 20, wherein the protective-carrier sheeting is provided in the form of separate sheets.